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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Haruhiko IKEDA

Serial No.: 09/927,053

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Group Art Unit: 1733

Examiner: --

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TC 1700

For: METHOD OF BONDING A CONDUCTIVE ADHESIVE AND AN ELECTRODE, AND  
A BONDED ELECTRODE OBTAINED THEREBY

United States Patent and Trademark Office  
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SUBMISSION

Sir:

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searching authority other than the PTO and the cited art together with a form listing the same for  
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I certify that each item of information contained in this Submission was cited  
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Respectfully submitted,

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Enclosures